



Connectors > PCB Connectors > Card Edge Connectors > Leadframes



Leadframe Type: **Single-In-Line (SIL)**

Connector System: **Board-to-Board**

Centerline (Pitch): **2.54 mm [.1 in]**

PCB Thickness (Accepted): **1.6 mm [.063 in]**

Standoff Height: **.8 mm [.031 in]**

Features

Product Type Features

Leadframe Type	Single-In-Line (SIL)
Connector System	Board-to-Board
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

Winding Direction	Down
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Body Features

Leadframe Clip Type	Y1
Leadframe Width	18.1 mm [.712 in]
Leadframe Clip Length	1.8 mm [.071 in]
Leadframe Thickness	.25 mm [.01 in]
Leadframe Hold-Down Feature	Without

Contact Features

Leadframe Pin Length	9.5 mm [.374 in]
Contact Base Material	Phosphor Bronze
Leadframe Plating Material	Tin

Termination Features

Termination Method to Printed Circuit Board	Through Hole - Solder
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Mechanical Attachment

Connector Mounting Type	Board Mount
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Housing Features

Centerline (Pitch)	2.54 mm[.1 in]
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Dimensions

Leadframe Gap Size	1.41 mm[.056 in]
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PCB Thickness (Accepted)	1.6 mm[.063 in]
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Standoff Height	.8 mm[.031 in]
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Packaging Features

Packaging Quantity	25000
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Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
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EU ELV Directive 2000/53/EC	Compliant
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China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
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EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
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Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
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Solder Process Capability	Wave solder capable to 265°C
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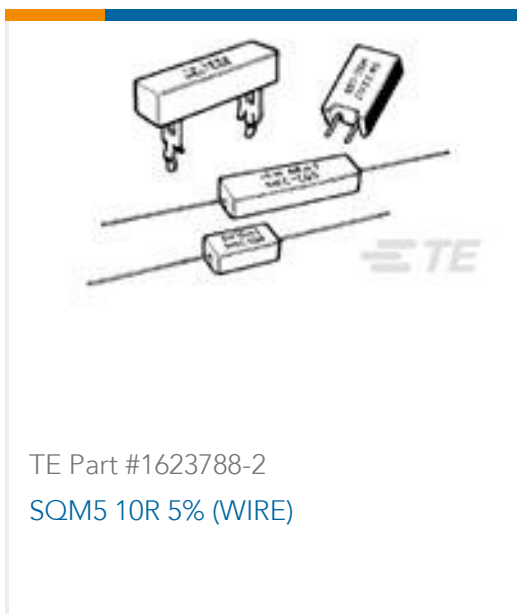
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



Customers Also Bought



Documents

Product Drawings

[CONTACT A SOUDER](#)

English

CAD Files

[Customer View Model](#)

[ENG_CVM_1544394-1_A.3d_igs.zip](#)

English

[Customer View Model](#)



[ENG_CVM_1544394-1_A.3d_stp.zip](#)

English

Customer View Model

[ENG_CVM_1544394-1_A.2d_dxf.zip](#)

English

3D PDF

English

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